#### DESCRIPTION

The SPN10T10 is the N-Channel enhancement mode power field effect transistor which is produced using super high cell density DMOS trench technology. The SPN10T10 has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low RDS(ON) and fast switching speed.

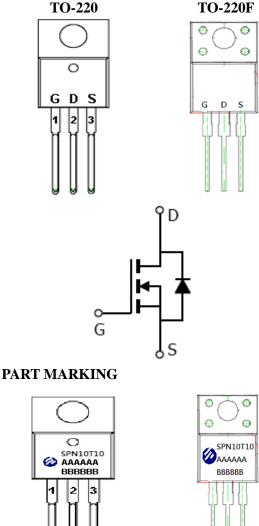
#### APPLICATIONS

- Powered System
- DC/DC Converter •
- Load Switch

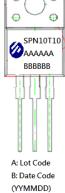
#### **FEATURES**

- 100V/5A,RDS(ON)=  $160m\Omega$ @VGS= 10V٠
- High density cell design for extremely low RDS (ON)
- Exceptional on-resistance and maximum DC current capability
- TO-220, TO-220F package design

### **PIN CONFIGURATION**



A : Lot Coue B : Date Code Code (YY/MM/DD)





# PIN DESCRIPTIONPinSymbolDescription1GGate2DDrain3SSource

#### **ORDERING INFORMATION**

Part Number	Package	Part Marking	
SPN10T10T220TGB	TO-220	SPN10T10	
SPN10T10T220FTGB	TO-220F	SPN10T10	

\* SPN10T10T220TGB : Tube ; Pb – Free ; Halogen - Free

X SPN10T10T220FTGB : Tube ; Pb – Free ; Halogen - Free

#### ABSOULTE MAXIMUM RATINGS

(TA=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		Vdss	100	V
Gate –Source Voltage		VGSS	±20	V
Continuous Dusin Compat/Tr. 150°C)	Tc=25°C	In	9	•
Continuous Drain Current(TJ=150°C)	Tc=100°C	ID	5.6	A
Pulsed Drain Current		Idм	30	А
Avalanche Current		IAS	9	А
Demon Dissingtion	$Tc = 25^{\circ}C$	D-	28	XX/
Power Dissipation	Tc=100°C	PD	10	W
Operating Junction Temperature		τJ	150	°C
Storage Temperature Range		Tstg	-55/150	°C
Thermal Resistance-Junction to Ambient		Reja	65	°C/W



#### ELECTRICAL CHARACTERISTICS

(TA= $25^{\circ}$ C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Тур	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V(BR)DSS	VGS=0V,ID=250uA	100			v	
Gate Threshold Voltage	VGS(th)	VDS=VGS,ID=250uA	1		3		
Gate Leakage Current	Igss	VDS=0V,VGS=±20V			±100	nA	
		Vds=80V,Vgs=0V			25	uA	
Zero Gate Voltage Drain Current	Idss	VDS=80V,VGS=0V TJ=125°C			250		
On-State Drain Current	ID(on)	VDS≥5V,VGS =10V	9			А	
Drain-Source On-Resistance	RDS(on)	Vgs= 10V, Id=5A		0.110	0.160	Ω	
Forward Transconductance	gfs	Vds=10V,Id=5A		5.6		S	
Diode Forward Voltage	Vsd	Is=9A,VGs =0V			1.3	V	
Dynamic							
Total Gate Charge	Qg			10	16	nC	
Gate-Source Charge	Qgs	$V_{DS}=80V, V_{GS}=10V$ ID= 5A		2.5			
Gate-Drain Charge	Qgd	1D- 571		4.5		1	
Input Capacitance	Ciss			430		pF	
Output Capacitance	Coss	VDS=25,VGS=0V f=1MHz		56			
Reverse Transfer Capacitance	Crss			35			
Turn-On Time	td(on)			6.5		nS	
	tr	$V_{DD}=50V,RL=10\Omega$		10			
	td(off)	ID= $5A$ , VGEN= $10V$ RG= $3.3\Omega$		13			
Turn-Off Time	tf			3.4			

#### TYPICAL CHARACTERISTICS

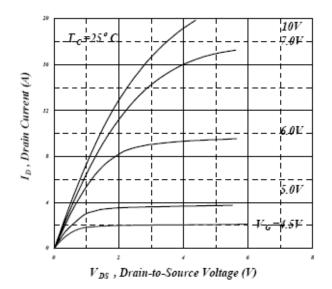


Fig 1. Typical Output Characteristics

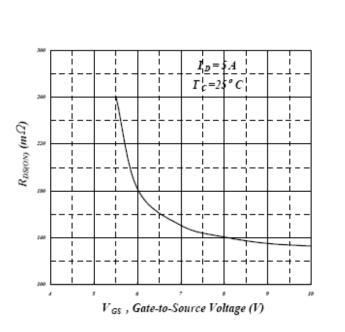


Fig 3. On-Resistance v.s. Gate Voltage

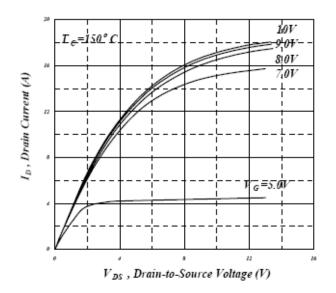


Fig 2. Typical Output Characteristics

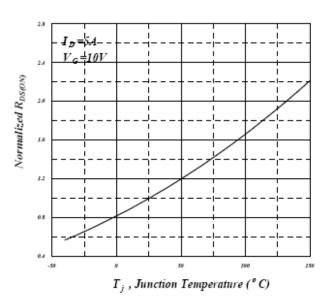


Fig 4. Normalized On-Resistance v.s. Junction Temperature

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### TYPICAL CHARACTERISTICS

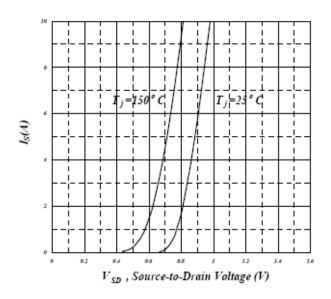


Fig 5. Forward Characteristic of Reverse Diode

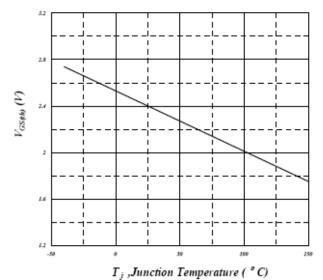


Fig 6. Gate Threshold Voltage v.s.

Junction Temperature

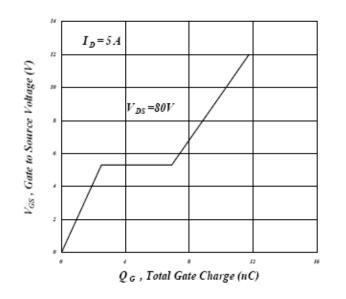


Fig 7. Gate Charge Characteristics

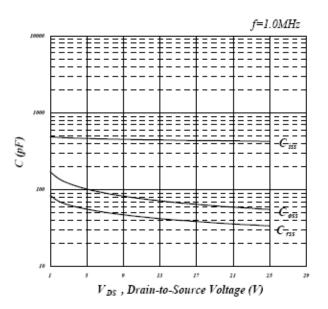
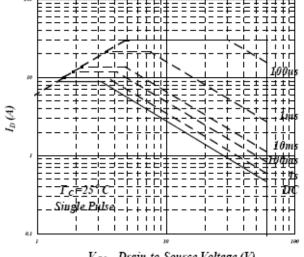


Fig 8. Typical Capacitance Characteristics



#### TYPICAL CHARACTERISTICS



V DS , Drain-to-Source Voltage (V)

Fig 9. Maximum Safe Operating Area

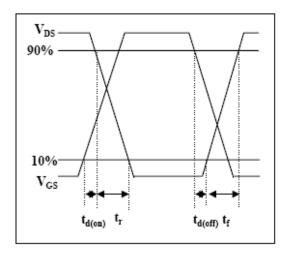


Fig 11. Switching Time Waveform

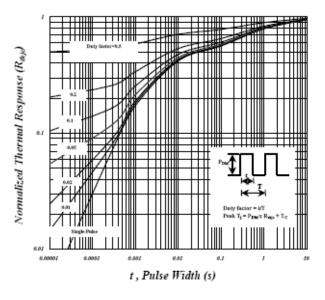


Fig 10. Effective Transient Thermal Impedance

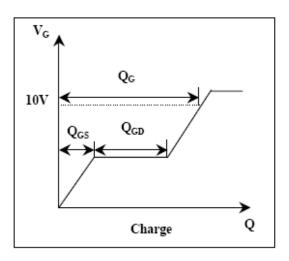
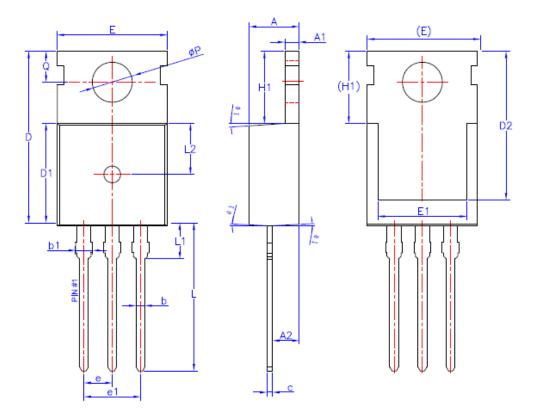


Fig 12. Gate Charge Waveform



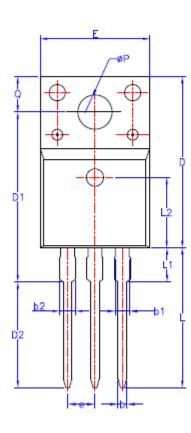
#### TO-220 PACKAGE OUTLINE

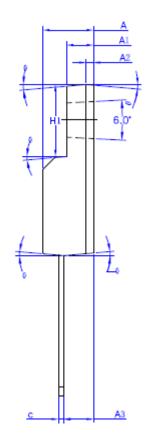


SYMBOL	MIN	NOM	MAX
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	—	0.90
b1	1.42	—	1.57
с	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	—	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
е	2.54BSC		
e1	5.08BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	-	—	3.50
L2	4.60REF		
øP	3.55	3.60	3.65
Q	2.73	—	2.87
θ1	1*	3*	5*



#### **TO-220F PACKAGE OUTLINE**





SYMBOL	MIN	NOM	MAX
		NOM	MAX
A	4.50	4.70	4.83
A1	2.34	2.54	2.74
A2	0.70 REF		
A3	2.56	2.76	2.93
Ь	0.70	_	0.90
b1	1.18	_	1.38
b2	—	_	1.47
с	0.45	0.50	0.60
D	15.67	15.87	16.07
D1	15.55	15.75	15.95
D2	9.60	9.80	10.0
E	9.96	10.16	10.36
е	2.54BSC		
H1	6.48	6.68	6.88
L	12.68	12.98	13.28
L1	_	_	3.50
L2	6.50REF		
ØP	3.08	3.18	3.28
Q	3.20	_	3.40
01	1°	3*	5*

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